



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Richard W. Wensel

Serial No.: 10/600,149

Filed: June 19, 2003

For: SEMICONDUCTOR DIE WITH
ATTACHED HEAT SINK AND
TRANSFER MOLD

Confirmation No.: 6258

Examiner: N. Ha

Group Art Unit: 2814

Attorney Docket No.: 2269-3061.8US
(96-0893.07/US)

Notice of Allowance Mailed:

November 4, 2004

NOTICE OF EXPRESS MAILING

Express Mail Mailing Label Number: EL994825043US

Date of Deposit with USPS: February 3, 2005

Person making Deposit: Steven P. Wong

AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

Serial No. 10/600,149

Amendments to the Specification begin on page 3 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 5 of this paper.

Remarks begin on page 8 of this paper.